

CLAIMS

1. A method of peeling a semiconductor chip, comprising the steps of:

peeling a semiconductor chip adhered to a  
5 tape from said tape by a peeling device including a plurality of annular contact members arranged one after another from the outside to the inside, wherein the plurality of annular contact members are operated so that the semiconductor chip is successively peeled off  
10 from the tape from an outer circumferential portion thereof toward a central portion thereof.

2. The method of peeling a semiconductor chip according to claim 1, wherein the plurality of annular contact members are simultaneously moved, and then, the  
15 outermost annular contact member in the plurality of annular contact members is stopped and the remaining annular contact members are further moved simultaneously.

3. A device for peeling a semiconductor chip  
20 adhered to a tape off from said tape, comprising:

a plurality of annular contact members arranged one after another from the outside to the inside; and

25 an operation device for operating the plurality of annular contact members so that the semiconductor chip is successively peeled, from the tape, from an outer circumferential portion thereof to a central portion thereof.

30 4. The device for peeling a semiconductor chip according to claim 3, wherein the operation device includes a cam for operating the plurality of annular contact members.

5. The device for peeling a semiconductor chip according to claim 3, further comprising a frame defining a vacuum chamber therein, a top plate arranged on said frame and having an opening, and a suction device arranged above said frame, said annular contact members being arranged in said frame.